

JAN 21 2004

**OFFICIAL**  
PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**DN 51343**

In re application of:  
Seita et al.

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Serial No.: 10/027,919

:

Filed: December 20, 2001

: Group Art Unit: 1753

For: ELECTROLYTIC COPPER PLATING  
SOLUTION AND METHOD FOR  
CONTROLLING THE SAME

: Examiner: Edna Wong

AMENDMENT

Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

In response to the Official Action mailed on October 21, 2003, Applicants submit the following amendments and remarks.

Amendments to the claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 6 of this paper.